



Product Change Notification: MFOL-13BACW955

Date:

16-Sep-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors, Digital Signal Controllers

Notification Subject:

CCB 8432 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional wire material, CRM-1064L as an additional die attach material, and G630AY as an additional mold compound for selected dsPIC33EP128xx, dsPIC33EP16GS202, dsPIC33EP256xx, dsPIC33EP32GS202, dsPIC33EV128GMxx, dsPIC33EV256GMxx, dsPIC33EV32GMxx, dsPIC33EV64GMxx, MGC3030, MCP3912, MCP3912B, MCP3919, MCP3919B, MCP3913, MCP3913B, PIC24EP128xx, PIC24EP256xx, PIC24FJ128Gxx, PIC24FJ64Gxx, PIC32MX110F016B, PIC32MX120F032B, PIC32MX130Fxx, PIC32MX150F128B, PIC32MX220F032B, PIC32MX210F016B, PIC32MX170F256B, PIC32MX230Fxx, PIC32MX250F128B, and PIC32MX270F256B device families available in 28L SSOP (.209in) package at MMT assembly site.

Affected CPNs:

[MFOL-13BACW955_Affected_CPN_09162026.pdf](#)

[MFOL-13BACW955_Affected_CPN_09162026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional wire material, CRM-1064L as an additional die attach material, and G630AY as an additional mold compound for selected dsPIC33EP128xx, dsPIC33EP16GS202, dsPIC33EP256xx, dsPIC33EP32GS202, dsPIC33EV128GMxx, dsPIC33EV256GMxx, dsPIC33EV32GMxx, dsPIC33EV64GMxx, MGC3030, MCP3912, MCP3912B, MCP3919, MCP3919B, MCP3913, MCP3913B, PIC24EP128xx, PIC24EP256xx, PIC24FJ128Gxx, PIC24FJ64Gxx, PIC32MX110F016B, PIC32MX120F032B, PIC32MX130Fxx, PIC32MX150F128B, PIC32MX220F032B, PIC32MX210F016B, PIC32MX170F256B, PIC32MX230Fxx, PIC32MX250F128B, and

PIC32MX270F256B device families available in 28L SSOP (.209in) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)		No
Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-free)	8390A (PFAS-free)	CRM- 1064L (PFAS-free)	Yes
Molding Compound Material	G600	G600	G630AY	Yes
Lead-Frame Material	CDA194	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as an additional wire material, CRM-1064L as an additional die attach material, and G630AY as an additional mold compound at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					>	November 2026				
Work Week	36	37	38	39	40		44	45	46	47	48
Initial PCN Issue Date			X								
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 16, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-13BACW955_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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